













OPA134, OPA2134, OPA4134

SBOS058A - DECEMBER 1997-REVISED OCTOBER 2015

OPAx134 SoundPlus™ High Performance Audio Operational Amplifiers

Features

Superior Sound Quality

Ultra Low Distortion: 0.00008%

Low Noise: 8 nV/√Hz True FET-Input: $I_B = 5pA$

High Speed:

Slew Rate: 20 V/µs Bandwidth: 8 MHz

High Open-Loop Gain: 120 dB (600 Ω) Wide Supply Range: ±2.5 V to ±18 V Single, Dual, and Quad Versions

Applications

Professional Audio and Music

Line Drivers

Line Receivers

Multimedia Audio

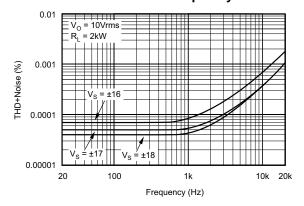
Active Filters

Preamplifiers

Integrators

Crossover Networks

THD+Noise vs Frequency



3 Description

The OPA134 series are ultra-low distortion, low-noise operational amplifiers fully specified for audio applications. A true FET input stage is incorporated to provide superior sound quality and speed for exceptional audio performance. This, in combination with high output drive capability and excellent DC performance, allows for use in a wide variety of demanding applications. In addition, the OPA134 has a wide output swing, to within 1 V of the rails, allowing increased headroom and making it ideal for use in any audio circuit.

OPA134 SoundPlus™ audio operational amplifiers are easy to use and free from phaseinversion and the overload problems often found in common FET-input operational amplifiers. They can be operated from ± 2.5 -V to ± 18 -V power supplies. Input cascode circuitry provides excellent commonmode rejection and maintains low input bias current over its wide input voltage range, minimizing distortion. OPA134 series operational amplifiers are unity-gain stable and provide excellent dynamic behavior over a wide range of load conditions, including high load capacitance. The dual and quad versions feature completely independent circuitry for lowest crosstalk and freedom from interaction, even when overdriven or overloaded.

Single and dual versions are available in 8-pin DIP and SO-8 surface-mount packages in standard configurations. The quad is available in 14-pin DIP and SO-14 surface mount packages. All are specified for -40°C to 85°C operation. A SPICE macromodel is available for design analysis.

Device Information(1)

PART NUMBER	PACKAGE BODY SIZE (N			
OPA134	SOIC (8)	3.91 mm × 4.90 mm		
	PDIP (8)	6.35 mm × 9.81 mm		
OD42424	SOIC (8)	3.91 mm × 4.90 mm		
OPA2134	PDIP (8)	6.35 mm × 9.81 mm		
OPA4134	SOIC (14)	3.91 mm × 8.65 mm		

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Table of Contents

1	Features 1	8 Application and Implementation	15
2	Applications 1	8.1 Application Information	15
3	Description 1	8.2 Typical Application	16
4	Revision History2	9 Power Supply Recommendations	18
5	Pin Configuration and Functions3	10 Layout	18
6	Specifications4	10.1 Layout Guidelines	
•	6.1 Absolute Maximum Ratings	10.2 Layout Example	19
	6.2 ESD Ratings	11 Device and Documentation Support	20
	6.3 Recommended Operating Conditions	11.1 Device Support	
	6.4 Electrical Characteristics	11.2 Documentation Support	20
	6.5 Typical Characteristics	11.3 Related Links	20
7	Detailed Description	11.4 Community Resources	<mark>2</mark> 1
-	7.1 Overview	11.5 Trademarks	21
	7.2 Functional Block Diagram	11.6 Electrostatic Discharge Caution	21
	7.3 Feature Description	11.7 Glossary	<mark>2</mark> 1
	7.4 Device Functional Modes	12 Mechanical, Packaging, and Orderable Information	21

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (September 2000) to Revision A

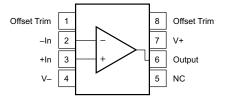
Page

Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section.

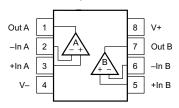


5 Pin Configuration and Functions

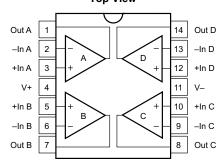
OPA134: P and D Packages 8-Pin PDIP and 8-Pin SOIC Top View



OPA2134: P and D Packages 8-Pin PDIP and 8-Pin SOIC Top View



OPA4134: P and D Packages 14-Pin PDIP and 14-Pin SOIC Top View



Pin Functions: OPA134

PIN		1/0	DESCRIPTION	
NAME	NO.	1/0	DESCRIPTION	
Offset Trim	1	I	Input offset voltage adjust	
-In	2	I	Inverting input	
+In	3	I	Noninverting input	
V-	4	_	Negative power supply	
NC	5	_	No internal connection. Can be left floating.	
Output	6	0	Output	
V+	7	_	Positive power supply	
Offset Trim	8	I	Input offset voltage adjust	

Pin Functions: OPA2134 and OPA4134

	PIN				
NAME	OPA2134 NO.	OPA4134 NO.	I/O	DESCRIPTION	
Out A	1	1	0	Output channel A	
−In A	2	2	I	Inverting input channel A	
+In A	3	3	I	Noninverting input channel A	
V+	8	4	_	Positive power supply	
+In B	5	5	I	Noninverting input channel B	
–In B	6	6	I	Inverting input channel B	
Out B	7	7	0	Output channel B	
Out C	_	8	0	Output channel C	
–In C	_	9	I	Inverting input channel C	
+In C	_	10	I	Noninverting input channel C	

Copyright © 1997–2015, Texas Instruments Incorporated



Pin Functions: OPA2134 and OPA4134 (continued)

	PIN				
NAME	OPA2134 NO.	OPA4134 NO.	1/0	DESCRIPTION	
V-	4	11	_	Negative power supply	
+In D	_	12	1	Noninverting input channel D	
–In D	_	13	1	Inverting input channel D	
Out D	_	14	0	Output channel D	

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
	Supply voltage, V+ to V-		36	V
	Input voltage	(V-) -0.7	(V+) +0.7	V
	Output short circuit ⁽²⁾		Continuous	
	Operating temperature	-40	125	°C
	Junction temperature		150	°C
	Lead temperature (soldering, 10 s)		300	°C
T _{stg}	Storage temperature	-55	125	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
OPA13	4 in PDIP and SOIC Packag	ge, OPA2134 and OPA4134 in PDIP Package		
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2000	V
OPA213	34 in SOIC Package			
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	
$V_{(ESD)}$	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±500	V
OPA41	34 in SOIC Package			
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	
V _(ESD)	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±200	V

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
VS	Supply voltage, $VS = (V+) - (V-)$	±2.5	±15	±18	V
T _A	Specified temperature	-40		85	°C

⁽²⁾ Short-circuit to ground, one amplifier per package.

²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



6.4 Electrical Characteristics

At $T_A = +25$ °C, $V_S = \pm 15$ V, unless otherwise noted

PAF	RAMETER	TEST CONDI	TIONS	MIN	TYP	MAX	UNIT
AUDIO PERFOR	MANCE					,	
Total Harmonia F	Notartian + Naina	G = 1, f = 1 kHz, V _O = 3	$R_L = 2 k\Omega$		0.00008%		
Total Harmonic D	DISTORTION + NOISE	Vrms	$R_L = 600 \Omega$		0.00015%		
Intermodulation Distortion		$G = 1, f = 1 \text{ kHz}, V_O = 1 \text{ Vp}$	p-p		-98		dB
Headroom ⁽¹⁾		THD < 0.01%, $R_L = 2 k\Omega$,	V _S = 18 V		23.6		dBu
FREQUENCY RE	ESPONSE						
Gain-Bandwidth	Product				8		MHz
Slew Rate ⁽²⁾				±15	±20		V/µs
Full Power Bandy	width				1.3		MHz
Settling Time 0.1	%	G = 1, 10-V Step, C _L = 100) pF		0.7		μs
Settling Time 0.0	1%	G = 1, 10-V Step, C _L = 100) pF		1		μs
Overload Recove	ery Time	$(V_{IN}) \times (Gain) = V_{S}$			0.5		μs
NOISE							
Input Voltage	Noise Voltage, f = 20 Hz to 20 kHz				1.2		μVrms
Noise Noise Density, f = 1 kHz					8		nV/√Hz
Current Noise De	ensity, f = 1 kHz				3		fA/√Hz
OFFSET VOLTA	GE	-		+			
		$T_A = -40$ °C to 85°C			±0.5	±2	.,
Input Offset Volta	age				±1 ±3 ⁽³		mV
Input Offset Volta	age vs Temperature	$T_A = -40$ °C to 85°C		±2		μV/°C	
Input Offset Volta (PSRR)	age vs Power Supply	V _S = ±2.5 V to ±18 V		90	106		dB
Channal Canarat	ion (Dual Quad)	DC, $R_L = 2 k\Omega$			135		٩D
Channel Seperat	ion (Duai, Quad)	$f = 20 \text{ kHz}, R_L = 2 \text{ k}\Omega$			130		dB
INPUT BIAS CU	RRENT					,	
Input Bias Currer	nt ⁽⁴⁾	$V_{CM} = 0 V$			5	±100	pА
Input Bias Currer	nt vs Temperature ⁽³⁾			See Typical Characteristics		±5	nA
Input Offset Curre	ent ⁽⁴⁾	V _{CM} = 0 V			±2	±50	рА
INPUT VOLTAG	E RANGE			1			-
Common-Mode \	/oltage Range			(V-)+2.5	13	(V+)-2.5	V
		$V_{CM} = -12.5 \text{ V to } 12.5 \text{ V}$		86	100		
Common-Mode Rejection		$T_A = -40$ °C to 85°C			90		dB
INPUT IMPEDAN	ICE			+			
Differential					10 ¹³ 2		Ω pF
Common-Mode		$V_{CM} = -12.5 \text{ V to } 12.5 \text{ V}$			10 ¹³ 5		Ω pF
OPEN-LOOP GA	IN	,		1			
		$R_L = 10 \text{ k}\Omega$, $V_O = -14.5 \text{ V}$	to 13.8 V	104	120		
Open-Loop Volta	ge Gain	$R_L = 2 k\Omega$, $V_O = -13.8 \text{ V to } 13.5 \text{ V}$		104	120		dB
. ,	-	$R_L = 600 \Omega$, $V_O = -12.8 \text{ V to } 12.5 \text{ V}$		104	120		

dBu = 20*log (Vrms/0.7746) where Vrms is the maximum output voltage for which THD+Noise is less than 0.01%. See THD+Noise text.

Product Folder Links: OPA134 OPA2134 OPA4134

⁽²⁾ (3) (4)

Proposed by design. Proposed by wafer-level test to 95% confidence level. High-speed test at $T_J = 25^{\circ}\text{C}$.



Electrical Characteristics (continued)

At $T_A = +25$ °C, $V_S = \pm 15$ V, unless otherwise noted

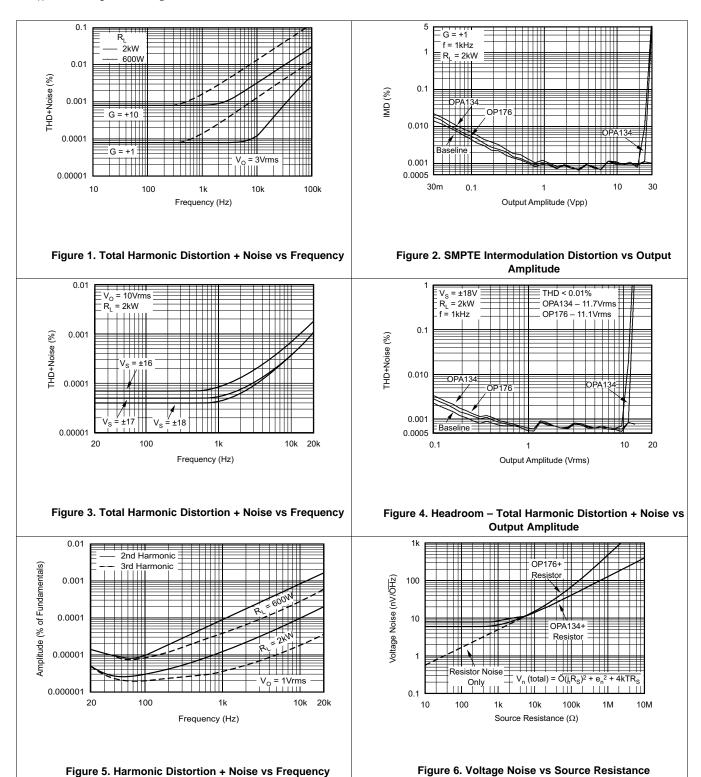
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OUTPUT					
	$R_L = 10 \text{ k}\Omega$	(V-)+0.5		(V+)-1.2	
Voltage Output	$R_L = 2 k\Omega$	(V-)+1.2		(V+)-1.5	V
	R _L = 600 Ω	(V-)+2.2		(V+)-2.5	
Output Current			±35		mA
Output Impedance, Closed-Loop (5)	f = 10 kHz		0.01		Ω
Output Impedance, Open-Loop	f = 10 kHz		10		Ω
Short-Circuit Current			±40		mA
Capacitive Lead Drive (Stable Operation)			e Typical cteristics		
POWER SUPPLY					
Specified Operating Voltage			±15		V
Operating Voltage Range		±2.5		±18	V
Quiescent Current (per amplifier)	I _O = 0		4	5	mA
TEMPERATURE RANGE		•		·	
Specified Range		-40		85	°C
Operating Range		-55		125	°C

⁽⁵⁾ See Figure 14



6.5 Typical Characteristics

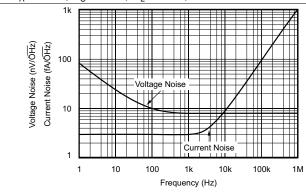
At $T_A = 25$ °C, $V_S = 15$ V, $R_L = 2$ k Ω , unless otherwise noted.



TEXAS INSTRUMENTS

Typical Characteristics (continued)

At $T_A = 25$ °C, $V_S = 15$ V, $R_L = 2$ k Ω , unless otherwise noted.



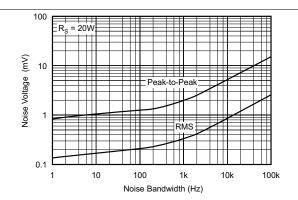
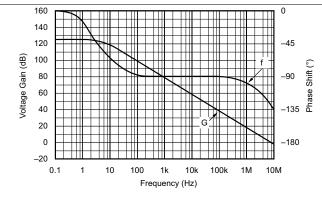


Figure 7. Input Voltage and Current Noise Spectral Density vs Frequency

Figure 8. Input-Referred Noise Voltage vs Noise Bandwidth



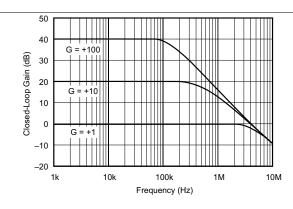
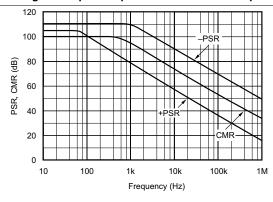


Figure 9. Open-Loop Gain and Phase vs Frequency

Figure 10. Closed-Loop Gain vs Frequency



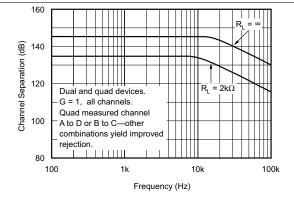


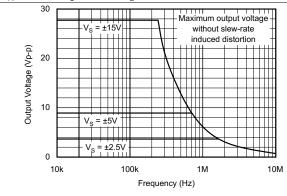
Figure 11. Power Supply and Common-Mode Rejection vs Frequency

Figure 12. Channel Separation vs Frequency



Typical Characteristics (continued)

At $T_A = 25$ °C, $V_S = 15$ V, $R_L = 2$ k Ω , unless otherwise noted.



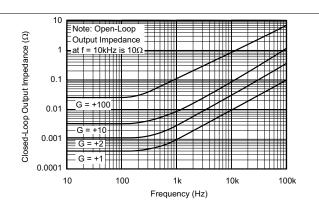
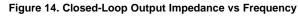
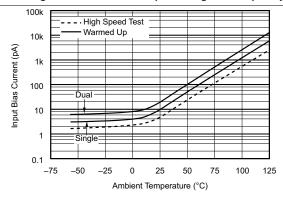


Figure 13. Maximum Output Voltage vs Frequency





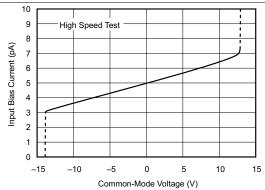
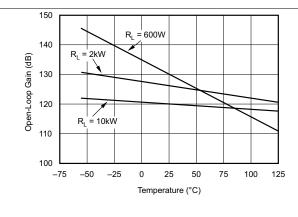


Figure 15. Input Bias Current vs Temperature

Figure 16. Input Bias Current vs Input Common-Mode Voltage



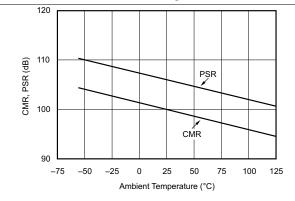


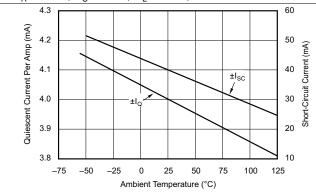
Figure 17. Open-Loop Gain vs Temperature

Figure 18. CMR, PSR vs Temperature

TEXAS INSTRUMENTS

Typical Characteristics (continued)

At $T_A = 25$ °C, $V_S = 15$ V, $R_L = 2$ k Ω , unless otherwise noted.



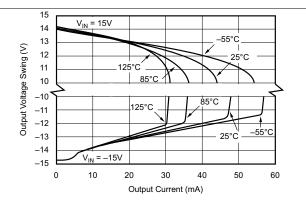
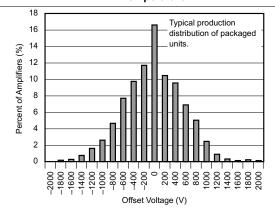


Figure 19. Quiescent Current and Short-Circuit Current vs
Temperature

Figure 20. Output Voltage Swing vs Output Current



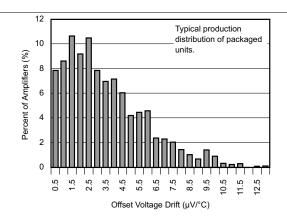
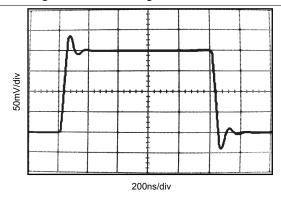


Figure 21. Offset Voltage Production Distribution

Figure 22. Offset Voltage Drift Production Distribution



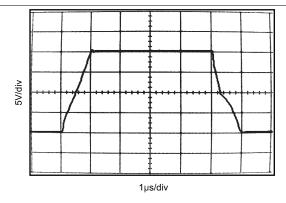


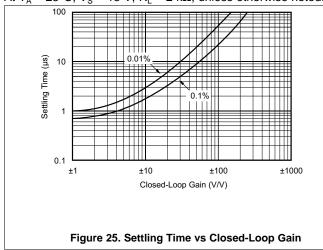
Figure 23. Small-Signal Step Response G = 1, $C_L = 100 pF$

Figure 24. Large-Signal Step Response G = 1, C_L = 100 pF



Typical Characteristics (continued)

At $T_A = 25$ °C, $V_S = 15$ V, $R_L = 2$ k Ω , unless otherwise noted.



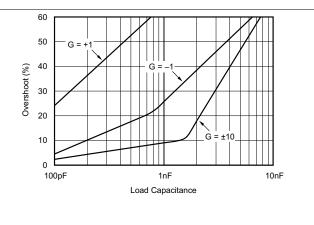


Figure 26. Small-Signal Overshoot vs Load Capacitance

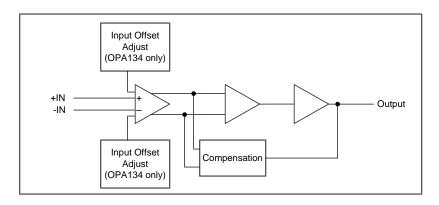


7 Detailed Description

7.1 Overview

The OPA134 series are ultra-low distortion, low-noise operational amplifiers fully specified for audio applications. A true FET input stage is incorporated to provide superior sound quality and speed for exceptional audio performance. This, in combination with high output drive capability and excellent DC performance, allows for use in a wide variety of demanding applications. In addition, the OPA134 has a wide output swing, to within 1 V of the rails, allowing increased headroom and making it ideal for use in any audio circuit.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Total Harmonic Distortion

The OPA134 series of operational amplifiers have excellent distortion characteristics. THD+Noise is below 0.0004% throughout the audio frequency range, 20 Hz to 20 kHz, with a 2-k Ω load. In addition, distortion remains relatively flat through its wide output voltage swing range, providing increased headroom compared to other audio amplifiers, including the OP176/275.

Headroom is a subjective measurement, and can be thought of as the maximum output amplitude allowed while still maintaining a low level of distortion. In an attempt to quantify headroom, TI defines very low distortion as 0.01%. Headroom is expressed as a ratio which compares the maximum allowable output voltage level to a standard output level (1 mW into 600 Ω , or 0.7746 Vrms). Therefore, OPA134 series of operational amplifiers, which have a maximum allowable output voltage level of 11.7 Vrms (THD+Noise < 0.01%), have a headroom specification of 23.6 dBu. See Figure 4.

7.3.2 Distortion Measurements

The distortion produced by OPA134 series of operational amplifiers is below the measurement limit of all known commercially-available equipment. However, a special test circuit can extend the measurement capabilities.

Operational amplifier distortion can be considered an internal error source which can be referred to the input. Figure 27 shows a circuit which causes the operational amplifier distortion to be 101 times greater than that which the operational amplifier normally produces. The addition of R3 to the otherwise standard non-inverting amplifier configuration alters the feedback factor or noise gain of the circuit. The closed-loop gain is unchanged, but the feedback available for error correction is reduced by a factor of 101, thus extending the resolution by 101. The input signal and load applied to the operational amplifier are the same as with conventional feedback without R3. The value of R3 should be kept small to minimize its effect on the distortion measurements.



Feature Description (continued)

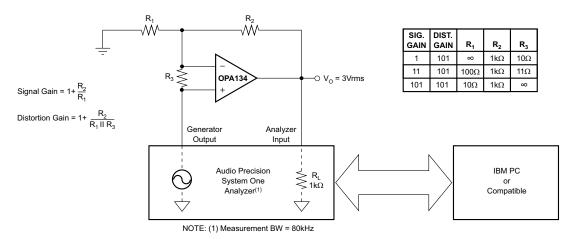


Figure 27. Distortion Test Circuit

This technique can be verified by duplicating measurements at high gain or high frequency, where the distortion is within the measurement capability of the test equipment. Measurements for this data sheet were made with an Audio Precision distortion and noise analyzer, which greatly simplifies repetitive measurements. The measurement technique can, however, be performed with manual distortion measurement instruments.

7.3.3 Source Impedance and Distortion

For lowest distortion with a source or feedback network with an impedance greater than 2 k Ω , the impedance seen by the positive and negative inputs in noninverting applications should be matched. The p-channel JFETs in the FET input stage exhibit a varying input capacitance with applied common-mode input voltage. In inverting configurations, the input does not vary with input voltage, because the inverting input is held at virtual ground. However, in noninverting applications the inputs do vary, and the gate-to-source voltage is not constant. The effect is increased distortion due to the varying capacitance for unmatched source impedances greater than 2 k Ω .

To maintain low distortion, match unbalanced source impedance with the appropriate values in the feedback network as shown in Figure 28. Of course, the unbalanced impedance may be from gain-setting resistors in the feedback path. If the parallel combination of R1 and R2 is greater than 2 $k\Omega$, use a matching impedance on the noninverting input. As always, minimize resistor values to reduce the effects of thermal noise.

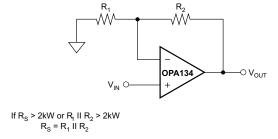


Figure 28. Impedance Matching for Maintaining Low Distortion in Non-Inverting Circuits

7.3.4 Phase Reversal Protection

The OPA134 series of operational amplifiers are free from output phase-reversal problems. Many audio operational amplifiers, such as the OP176, exhibit phase-reversal of the output when the input common-mode voltage range is exceeded. This can occur in voltage-follower circuits, causing serious problems in control loop applications. The OPA134 series operational amplifiers are free from this undesirable behavior even with inputs of 10-V beyond the input common-mode range.

Copyright © 1997–2015, Texas Instruments Incorporated



Feature Description (continued)

7.3.5 Output Current Limit

Output current is limited by internal circuitry to approximately ±40 mA at 25°C. The limit current decreases with increasing temperature, as shown in Figure 19.

7.4 Device Functional Modes

7.4.1 Noise Performance

Circuit noise is determined by the thermal noise of external resistors and operational amplifier noise. Operational amplifier noise is described by two parameters: noise voltage and noise current. The total noise is quantified by the equation:

$$V_{n}(total) = \sqrt{(i_{n}R_{S})^{2}e_{n}^{2} + 4kTR_{S}}$$
(1)

With low source impedance, the current noise term is insignificant and voltage noise dominates the noise performance. At high source impedance, the current noise term becomes the dominant contributor.

Low-noise bipolar operational amplifiers such as the OPA27 and OPA37 provide low voltage noise at the expense of a higher current noise. However, OPA134 series operational amplifiers provide both low voltage noise and low current noise. This provides optimum noise performance over a wide range of sources, including reactive source impedances; refer to Figure 6. Above 2-k Ω source resistance, the operational amplifier contributes little additional noise; the voltage and current terms in the total noise equation become insignificant and the source resistance term dominates. Below 2 k Ω , operational amplifier voltage noise dominates over the resistor noise, but compares favorably with other audio operational amplifiers such as the OP176.

Submit Documentation Feedback

Copyright © 1997–2015, Texas Instruments Incorporated



8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The OPA134 series operational amplifiers are unity-gain stable, and suitable for a wide range of audio and general-purpose applications. All circuitry is independent in the dual version, assuring normal behavior when one amplifier in a package is overdriven or short-circuited. Power supply pins should be bypassed with 10-nF ceramic capacitors or larger to minimize power supply noise.

8.1.1 Operating Voltage

The OPA134 series of operational amplifiers operate with power supplies from ±2.5 V to ±18 V with excellent performance. Although specifications are production tested with ±15-V supplies, most behavior remains unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltage are shown in *Typical Characteristics*.

8.1.2 Offset Voltage Trim

Offset voltage of OPA134 series amplifiers is laser-trimmed, and usually requires no user adjustment. The OPA134 (single operational amplifier version) provides offset trim connections on pins 1 and 8, identical to 5534 amplifiers. Offset voltage can be adjusted by connecting a potentiometer as shown in Figure 29. This adjustment should be used only to null the offset of the operational amplifier, not to adjust system offset or offset produced by the signal source. Nulling offset could change the offset voltage drift behavior of the operational amplifier. While it is not possible to predict the exact change in drift, the effect is usually small.

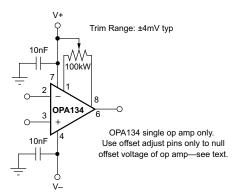


Figure 29. OPA134 Offset Voltage Trim Circuit

Copyright © 1997–2015, Texas Instruments Incorporated

Submit Documentation Feedback



8.2 Typical Application

The OPAx134 family offers outstanding dc precision and AC performance. These devices operate up to 36-V supply rails and offer ultralow distortion and noise, as well as 8-MHz bandwidth and high capacitive load drive. These features make the OPAx134 a robust, high-performance operational amplifier for high-voltage professional audio applications.

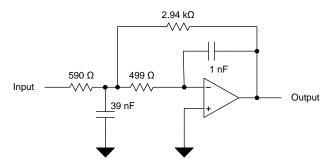


Figure 30. OPA134 2nd Order 30-kHz, Low Pass Filter Schematic

8.2.1 Design Requirements

- Gain = 5 V/V (inverting)
- Low pass cutoff frequency = 30 kHz
- -40 db/dec filter response
- Maintain less than 3-dB gain peaking in the gain versus frequency response

8.2.2 Detailed Design Procedure

The infinite-gain multiple-feedback circuit for a low-pass network function is shown in Figure 30. The voltage transfer function is:

$$\frac{\text{Output}}{\text{Input}}(s) = \frac{-1/R_1R_3C_2C_5}{s^2 + (s/C_2)(1/R_1 + 1/R_3 + 1/R_4) + 1/R_3R_4C_2C_5}$$
 (2)

This circuit produces a signal inversion. For this circuit the gain at DC and the low pass cutoff frequency are calculated using Equation 3.

Gain =
$$\frac{R_4}{R_1}$$

 $f_C = \frac{1}{2\pi} \sqrt{(1/R_3 R_4 C_2 C_5)}$ (3)

Software tools are readily available to simplify filter design. WEBENCH® Filter Designer is a simple, powerful, and easy-to-use active filter design program. The WEBENCH Filter Designer lets you create optimized filter designs using a selection of TI operational amplifiers and passive components from TI's vendor partners.

Available as a web based tool from the WEBENCH® Design Center, WEBENCH® Filter Designer allows you to design, optimize, and simulate complete multistage active filter solutions within minutes.



Typical Application (continued)

8.2.3 Application Curve

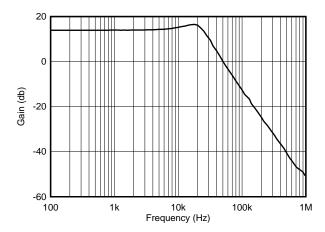


Figure 31. OPA134 2nd Order 30-kHz, Low Pass Filter Response



9 Power Supply Recommendations

The OPAx134 is specified for operation from 5 V to 36 V (±2.5 V to ±18 V); many specifications apply from –40°C to 85°C. Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in the *Typical Characteristics*.

CAUTION

Supply voltages larger than 36 V can permanently damage the device; see the *Absolute Maximum Ratings*.

Place 10-nF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies. For more detailed information on bypass capacitor placement, see the *Layout Guidelines*.

10 Layout

10.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

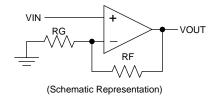
- Noise can propagate into analog circuitry through the power pins of the circuit as a whole and operational
 amplifier itself. Bypass capacitors are used to reduce the coupled noise by providing low-impedance power
 sources local to the analog circuitry.
 - Connect low-ESR, 10-nF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for singlesupply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective
 methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes.
 A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital
 and analog grounds paying attention to the flow of the ground current. For more detailed information refer to
 Circuit Board Layout Techniques, SLOA089.
- In order to reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If these traces cannot be kept separate, crossing the sensitive trace perpendicular is much better as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. As shown in *Layout Example*, keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.
- Cleaning the PCB following board assembly is recommended for best performance.
- Any precision integrated circuit may experience performance shifts due to moisture ingress into the plastic package. Following any aqueous PCB cleaning process, baking the PCB assembly is recommended to remove moisture introduced into the device packaging during the cleaning process. A low temperature, post cleaning bake at 85°C for 30 minutes is sufficient for most circumstances.

Submit Documentation Feedback

Copyright © 1997–2015, Texas Instruments Incorporated



10.2 Layout Example



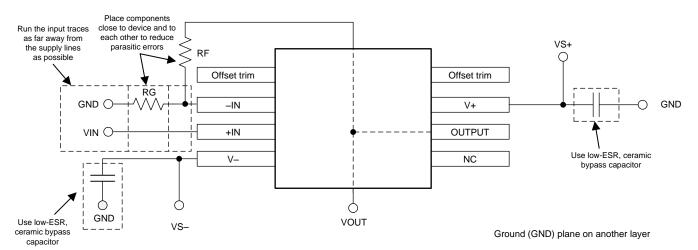


Figure 32. OPA134 Layout Example for the Noninverting Configuration

Copyright © 1997–2015, Texas Instruments Incorporated



11 Device and Documentation Support

11.1 Device Support

11.1.1 Development Support

11.1.1.1 WEBENCH Filter Designer Tool

WEBENCH® Filter Designer is a simple, powerful, and easy-to-use active filter design program. The WEBENCH Filter Designer lets you create optimized filter designs using a selection of TI operational amplifiers and passive components from TI's vendor partners.

11.1.1.2 TINA-TI™ (Free Software Download)

TINA™ is a simple, powerful, and easy-to-use circuit simulation program based on a SPICE engine. TINA-TI is a free, fully-functional version of the TINA software, preloaded with a library of macro models in addition to a range of both passive and active models. TINA-TI provides all the conventional dc, transient, and frequency domain analysis of SPICE, as well as additional design capabilities.

Available as a free download from the Analog eLab Design Center, TINA-TI offers extensive post-processing capability that allows users to format results in a variety of ways. Virtual instruments offer the ability to select input waveforms and probe circuit nodes, voltages, and waveforms, creating a dynamic quick-start tool.

NOTE

These files require that either the TINA software (from DesignSoft™) or TINA-TI software be installed. Download the free TINA-TI software from the TINA-TI folder.

11.1.1.3 TI Precision Designs

The OPAx134 is featured in several TI Precision Designs, available online at http://www.ti.com/ww/en/analog/precision-designs/. TI Precision Designs are analog solutions created by TI's precision analog applications experts and offer the theory of operation, component selection, simulation, complete PCB schematic and layout, bill of materials, and measured performance of many useful circuits.

11.2 Documentation Support

11.2.1 Related Documentation

For related documentation, see the following:

- EMI Rejection Ratio of Operational Amplifiers, SBOA128
- Circuit Board Layout Techniques, SLOA089

11.3 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
OPA134	Click here	Click here	Click here	Click here	Click here
OPA2134	Click here	Click here	Click here	Click here	Click here
OPA4134	Click here	Click here	Click here	Click here	Click here



11.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.5 Trademarks

SoundPlus, TINA-TI, E2E are trademarks of Texas Instruments. TINA, DesignSoft are trademarks of DesignSoft, Inc. All other trademarks are the property of their respective owners.

11.6 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.7 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Product Folder Links: OPA134 OPA2134 OPA4134

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic Security www.ti.com/security logic.ti.com

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity